Silicon N Channel Dual Gate MOS FET UHF / VHF RF Amplifier

HITACHI

ADE-208-449 1st. Edition

WWW.DZSC.CO

Features

- Low noise figure NF = 1.0 dB typ. at f = 200 MHz
- High gain
 PG = 27.6 dB typ. at f = 200 MHz

MPAK-4

Outline

- 1. Source
- 2. Gate1
- 3. Gate2
- 4. Drain



Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

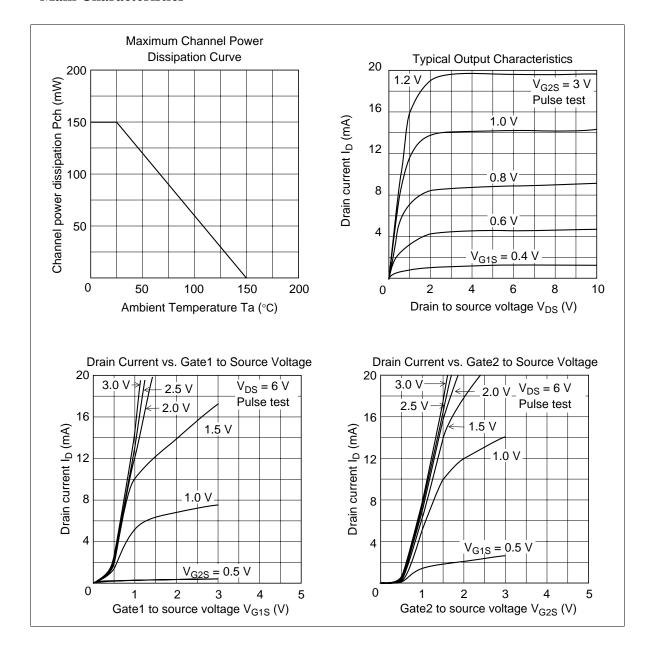
Item	Symbol	Ratings	Unit	
Drain to source voltage	V_{DS}	14	V	
Gate 1 to source voltage	V _{G1S}	±8	V	
Gate 2 to source voltage	V_{G2S}	±8	V	
Drain current	I _D	25	mA	
Channel power dissipation	Pch	150	mW	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

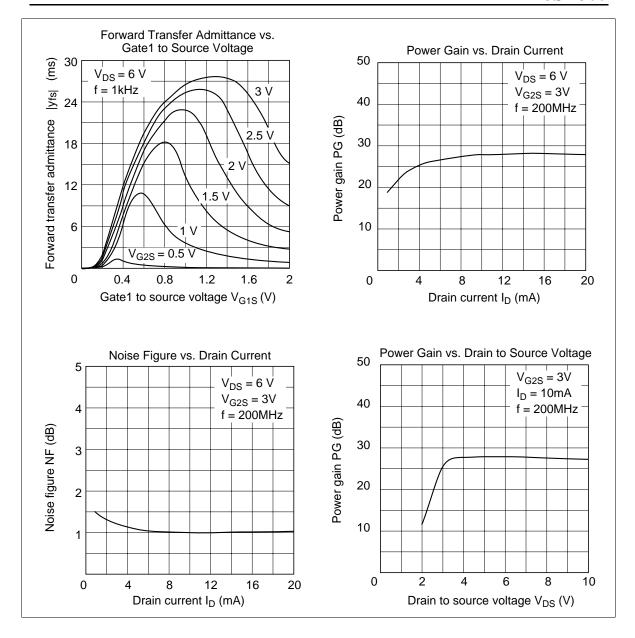
Electrical Characteristics ($Ta = 25^{\circ}C$)

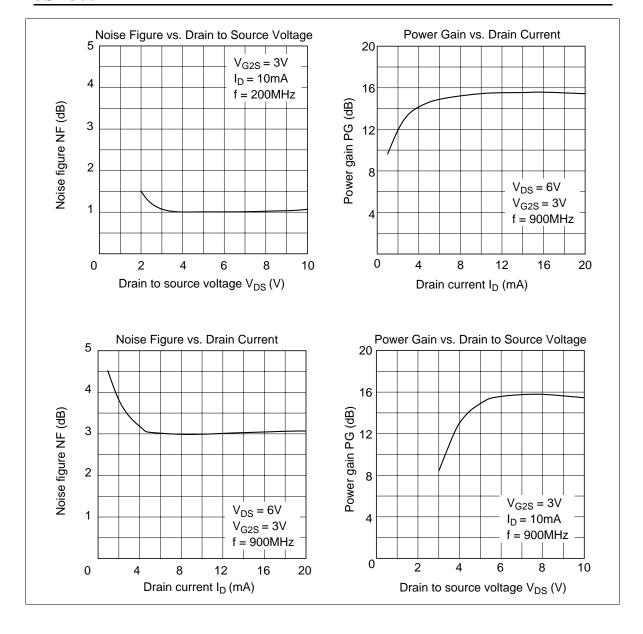
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSX}$	14	_	_	V	$I_D = 200 \mu A, V_{G1S} = -3 V,$ $V_{G2S} = -3 V$
Gate 1 to source breakdown voltage	$V_{(BR)G1SS}$	±8	_	_	V	$I_{G1} = \pm 10 \mu A,$ $V_{DS} = V_{G2S} = 0$
Gate 2 to source breakdown voltage	$V_{(BR)G2SS}$	±8	_	_	V	$I_{G2} = \pm 10 \mu A,$ $V_{DS} = V_{G1S} = 0$
Gate 1 cutoff current	I _{G1SS}	_	_	±100	nA	$V_{G1S} = \pm 6 V,$ $V_{DS} = V_{G2S} = 0$
Gate 2 cutoff current	I _{G2SS}	_	_	±100	nA	$V_{G2S} = \pm 6 V,$ $V_{DS} = V_{G1S} = 0$
Drain current	I _{DS(op)}	4	8	14	mA	$V_{DS} = 6 \text{ V}, V_{G1S} = 0.75 \text{ V}, V_{G2S} = 3 \text{ V}$
Gate 1 to source cutoff voltage	$V_{\text{G1S(off)}}$	0	+0.2	+1.0	V	$V_{DS} = 10 \text{ V}, V_{G2S} = 3 \text{ V},$ $I_{D} = 100 \mu\text{A}$
Gate 2 to source cutoff voltage	$V_{\text{G2S(off)}}$	0	+0.3	+1.0	V	$V_{DS} = 10 \text{ V}, V_{G1S} = 3 \text{ V},$ $I_{D} = 100 \mu\text{A}$
Forward transfer admittance	y _{fs}	20	25	_	ms	$V_{DS} = 6 \text{ V}, V_{G2S} = 3 \text{ V},$ $I_{D} = 10 \text{ mA}, f = 1 \text{ kHz}$
Input capacitance	Ciss	2.4	3.1	3.5	pF	V _{DS} = 6 V,
Output capacitance	Coss	0.8	1.1	1.4	pF	$V_{G2S} = 3 \text{ V}, I_{D} = 10 \text{ mA}$
Reverse transfer capacitance	Crss	_	0.021	0.04	pF	f = 1 MHz
Power gain	PG	24	27.6	_	dB	$V_{DS} = 6 \text{ V}, V_{G2S} = 3 \text{ V},$
Noise figure	NF	_	1.0	1.5	dB	$I_{D} = 10 \text{ mA}, f = 200 \text{ MHz}$
Power gain	PG	12	15.6	_	dB	$V_{DS} = 6 \text{ V}, V_{G2S} = 3 \text{ V},$
Noise figure	NF	_	3.0	4.0	dB	I _D = 10 mA, f = 900 MHz
Noise figure	NF		2.7	3.5	dB	$V_{DS} = 6 \text{ V}, V_{G2S} = 3 \text{ V},$ $I_{D} = 10 \text{ mA}, f = 60 \text{ MHz}$

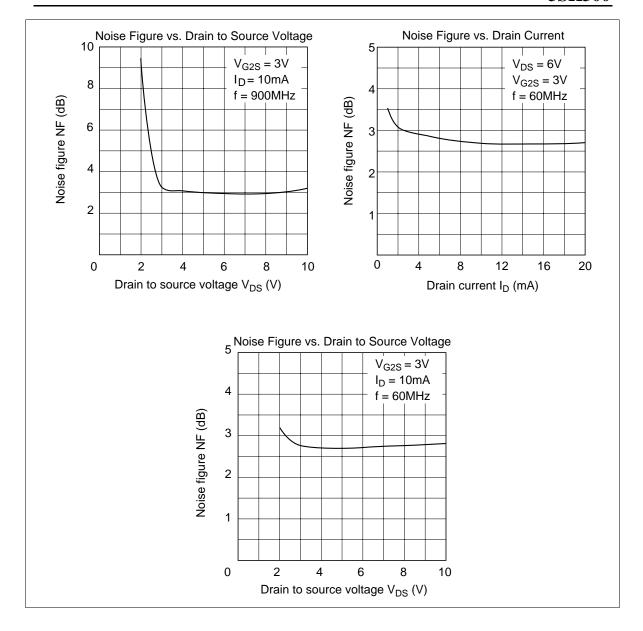
Note: Marking is "ZR-"

Main Characteristics



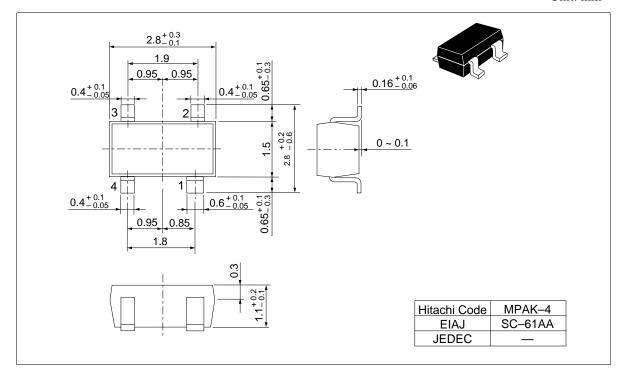






Package Dimentions

Unit: mm



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